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Integracija procesne naprave (FDI®) - 4. del: Paketi FDI (IEC 62769-4:2023)

Field Device Integration (FDI®) - Part 4: FDI Packages (IEC 62769-4:2023)

Feldgeräteintegration (FDI®) - Teil 4: FDI-Packages (IEC 62769-4:2023)

Intégration des appareils de terrain (FDI®) - Partie 4: Paquetages FDI (IEC 62769-4:2023)

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Intégration des appareils de terrain (FDI®) - Partie 4:
Paquetages FDI
(IEC 62769-4:2023)

Feldgeräteintegration (FDI®) - Teil 4: FDI-Packages
(IEC 62769-4:2023)

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EN IEC 62769-4:2023 (E)**European foreword**

The text of document 65E/857/CDV, future edition 3 of IEC 62769-4, prepared by SC 65E "Devices and integration in enterprise systems" of IEC/TC 65 "Industrial-process measurement, control and automation" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62769-4:2023.

The following dates are fixed:

- latest date by which the document has to be implemented at national (dop) 2024-02-10 level by publication of an identical national standard or by endorsement
- latest date by which the national standards conflicting with the (dow) 2026-05-10 document have to be withdrawn

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 61784-1-1:2023 NOTE Approved as EN IEC 61784-1-1:2023 (not modified)

IEC 61784-1-3:2023 NOTE Approved as EN IEC 61784-1-3:2023 (not modified)

IEC 61784-1-9:2023 NOTE Approved as EN IEC 61784-1-9:2023 (not modified)

IEC 62591 NOTE Approved as EN 62591

IEC 62734 NOTE Approved as EN 62734

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61804-3	-	Devices and integration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 3: EDDL syntax and semantics	EN IEC 61804-3	-
IEC 61804-5	2020	Devices and intergration in enterprise systems - Function blocks (FB) for process control and electronic device description language (EDDL) - Part 5: EDDL Builtin library	EN IEC 61804-5	2020
IEC 62769-1	-	Field Device Integration (FDI®) - Part 1: Overview	EN IEC 62769-1	-
IEC 62769-2	-	Field Device Integration (FDI®) - Part 2: Client	EN IEC 62769-2	-
IEC 62769-5	-	Field Device Integration (FDI®) - Part 5: FDI Information Model	EN IEC 62769-5	-
IEC 62769-6	-	Field Device Integration (FDI®) - Part 6: FDI Technology Mappings	EN IEC 62769-6	-
IEC 62769-7	-	Field Device Integration (FDI®) - Part 7: Communication Devices	EN IEC 62769-7	-
IEC 62769-1xx	series	Field device integration (FDI®) - Part 1xx-y: Profiles	-	-
ISO/IEC 11578	-	Information technology - Open Systems Interconnection - Remote Procedure Call (RPC)	-	-
ISO/IEC 29500-2	2021	Document description and processing languages - Office Open XML file formats - Part 2: Open packaging conventions	-	-
ISO 639-1	-	Codes for the representation of names of languages - Part 1: Alpha-2 code	-	-
ISO 32000-1	-	Document management - Portable document format - Part 1: PDF 1.7	-	-

EN IEC 62769-4:2023 (E)

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
Dublin Core Metadata Initiative	2020	DCMI Metadata Terms	-	-
FCG TS10099	-	Field Device Integration (FDI®) - Technology Management	-	-
FIPS 140-3	2019	Security Requirements for Cryptographic Modules	-	-
ETSI EN 319 132-1	-	Electronic Signatures and Infrastructures (ESI); XAdES digital signatures; Part 1: Building blocks and XAdES baseline signatures	-	-
ETSI TS 101 733	-	Electronic Signatures and Infrastructures (ESI); CMS Advanced Electronic Signatures (CAAdES)	-	-

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NORME INTERNATIONALE



**Field Device Integration (FDI®) –
Part 4: FDI Packages**

**Intégration des appareils de terrain (FDI®) –
Partie 4: Paquetages FDI**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE INTEGRATION (FDI®) –**Part 4: FDI® Packages****FOREWORD**

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as “IEC Publication(s)”). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC 62769-4 has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation. It is an International Standard.

This third edition cancels and replaces the second edition published in 2021. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added DocumentClass to Package Schema, Description of Feature Table and Documentation Catalog, individual schemas for Feature Table and Package Documentation Catalog, schema for UnitConversion, interactive download to device, and Feature Unit Conversion;
- b) moved DocumentClass to Package Documentation Catalog Schema;
- c) updated Description of Feature Table updated XML schema for Feature Table.